

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
a plurality of laminated semiconductor elements; and
highly water-absorbing resin films formed between the semiconductor elements, wherein
the highly water-absorbing resin films absorb an organic solvent having a boiling point
equal to or higher than the reflow melting point temperature of solder.

2. (Cancelled)

3. (Cancelled)

4. (Original) The semiconductor device according to claim 1, further comprising heat-dissipating heat sinks installed on the sides of the plurality of laminated semiconductor elements.

5. (Withdrawn) A semiconductor device comprising:
a plurality of laminated semiconductor elements; and
conductive resin films formed on the whole areas between the semiconductor elements.

6. (Withdrawn) A semiconductor device comprising:
a plurality of laminated semiconductor elements;

metal plates provided between the semiconductor elements; and
inner bumps for electrically connecting adjacent semiconductor elements with each other;
wherein each of the metal plates have openings, whose circumferences have been
subjected to insulation treatment, in locations where the inner bumps pass.

7. (Withdrawn) The semiconductor device according to claim 6, further comprising
highly water-absorbing resin films formed between the semiconductor elements.